


NOTES, UNLESS OTHERWISE SPECIFIED:

1. The netname "DMD_P3P3V" represents connection to the +3.3V digital power plane.
2. The symbol  represents connection to the digital ground plane.
3. A "Z" suffix on a signal name indicates an active low signal.
4. All components with designators "U", "D", "Y" and "Q" are electrostatic discharge sensitive.
5. All resistor values are in ohms, 1/16W and 5% unless otherwise specified.

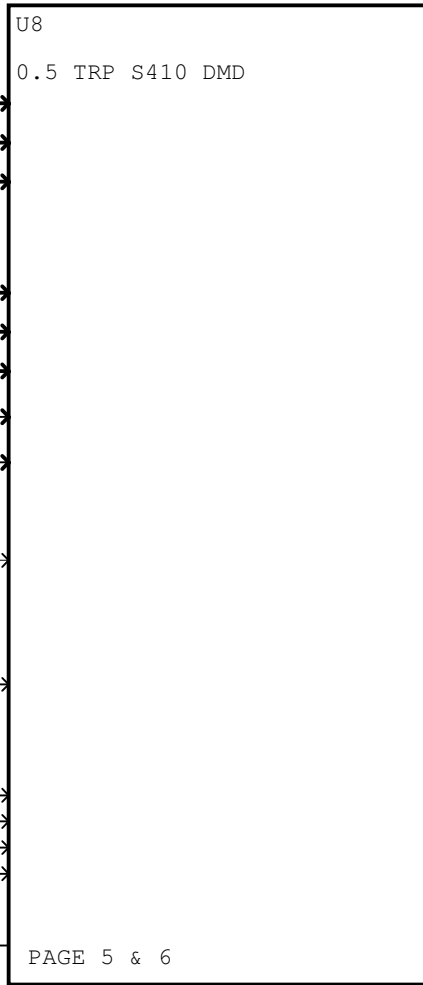
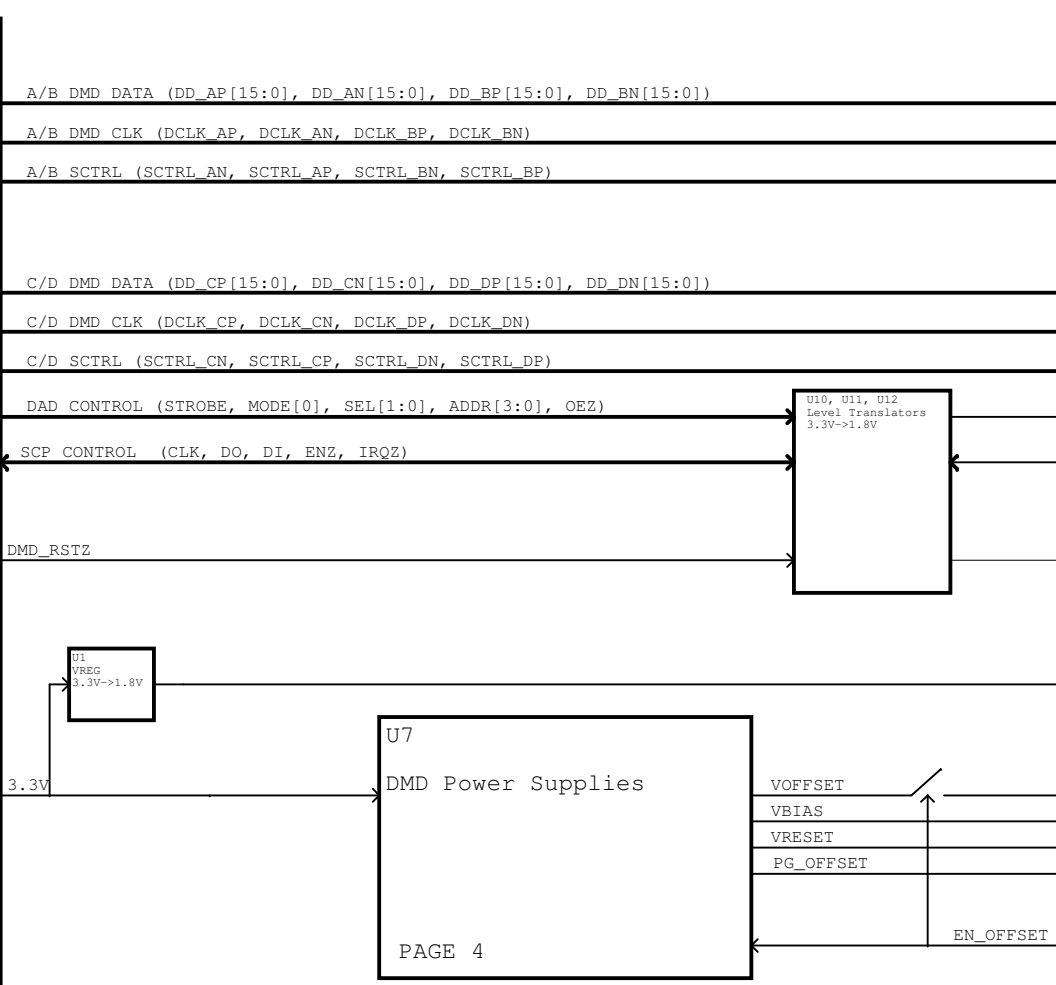
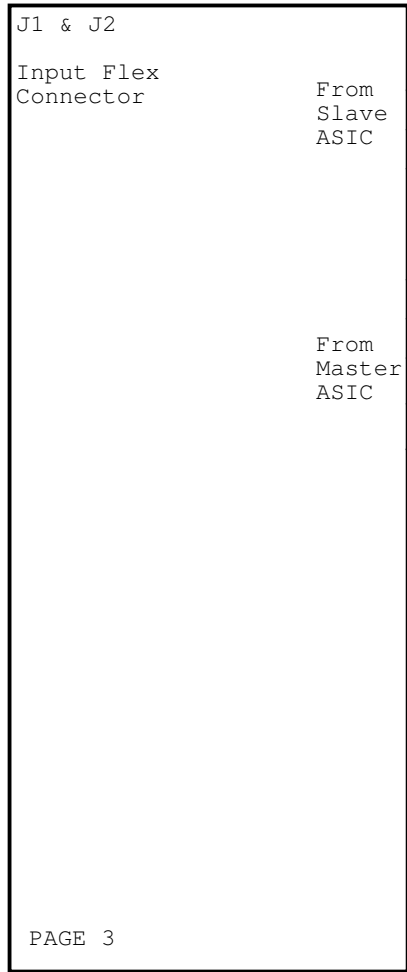
COMPUTER GENERATED DRAWING. DO NOT REVISE MANUALLY			
REVISIONS			
REV	DESCRIPTION	DATE	APPROVED
A	ECO 2161773: Initial Release		

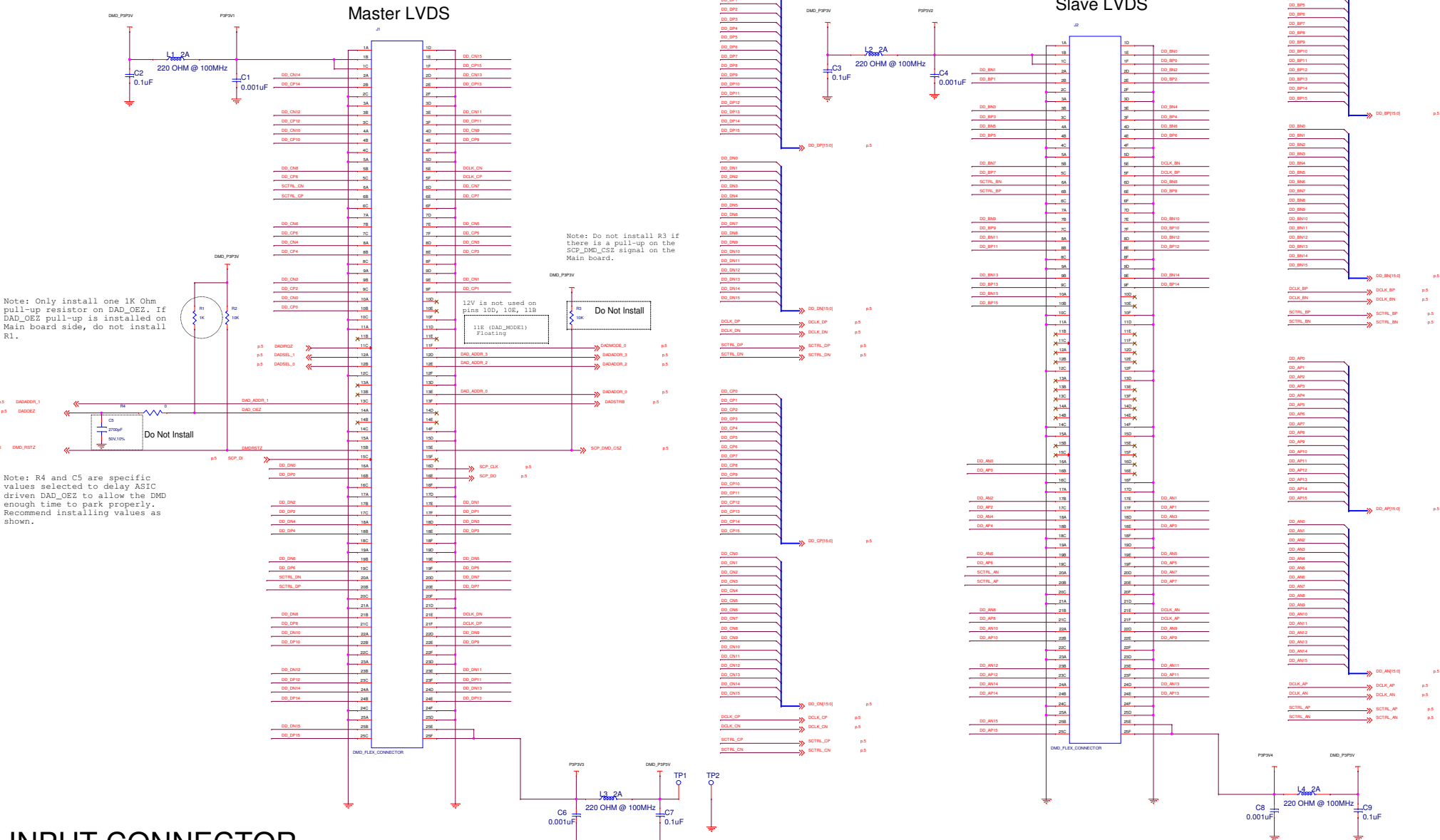
HIGHEST REFERENCE DESIGNATORS USED					



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		ENGR	Ben Uhing	8/24/2016		
		SVST	Mike McCormick	8/24/2016		
		FRU	John O'Connor	8/24/2016		
		APVD	Jack Gregory	8/24/2016		TITLE
2515296	0314AS					TIDA-01474 DMD Board Schematic
NEXT ASSY	USED ON					D
		SW	Cadence 16.6			DRAWING NO
						2515294
						SCALE
						SHEET
						1 of 7
						REV
						A



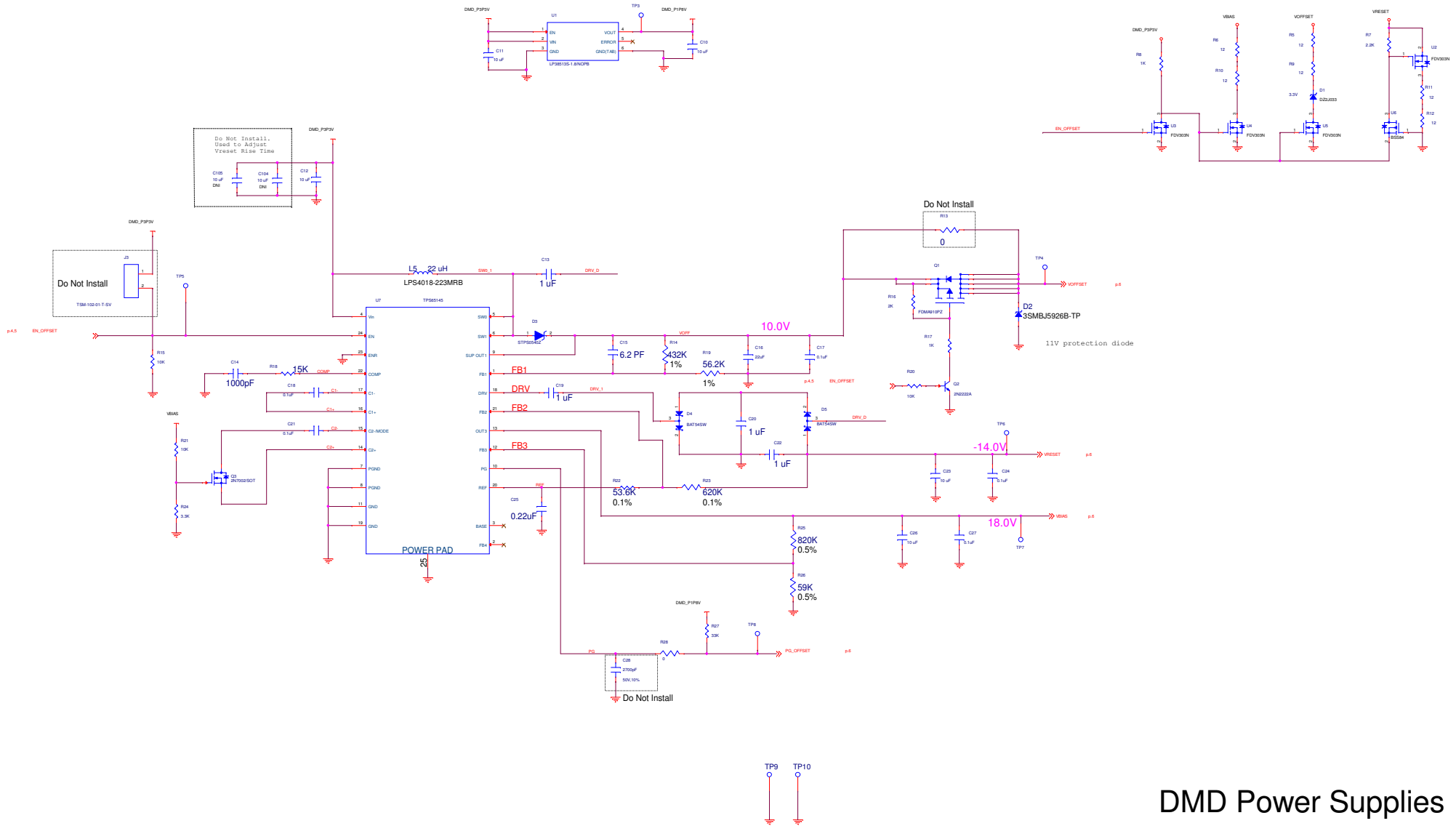


INPUT CONNECTOR

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	<small>ISSUE DATE</small>	<small>SCALE</small>	<small>SHEET 3 OF 7</small>

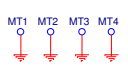
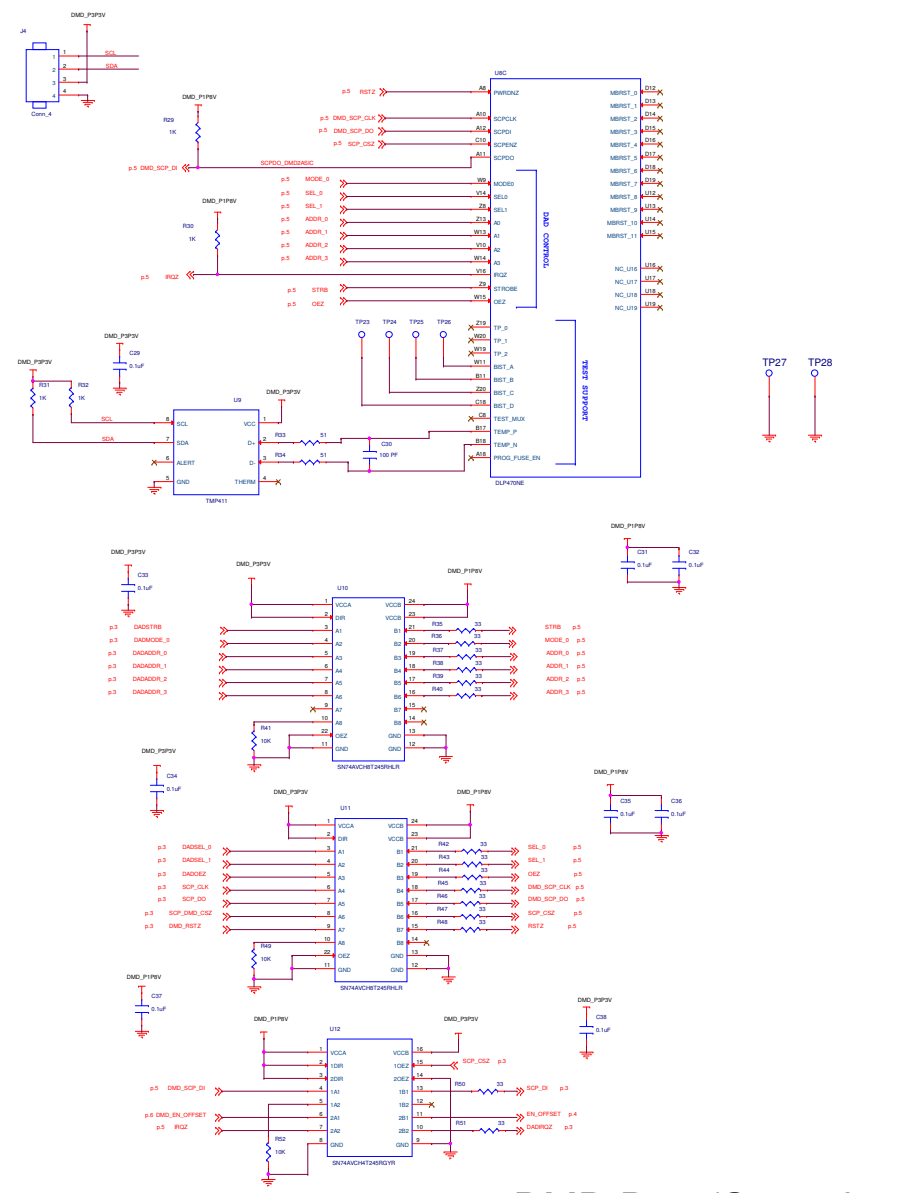
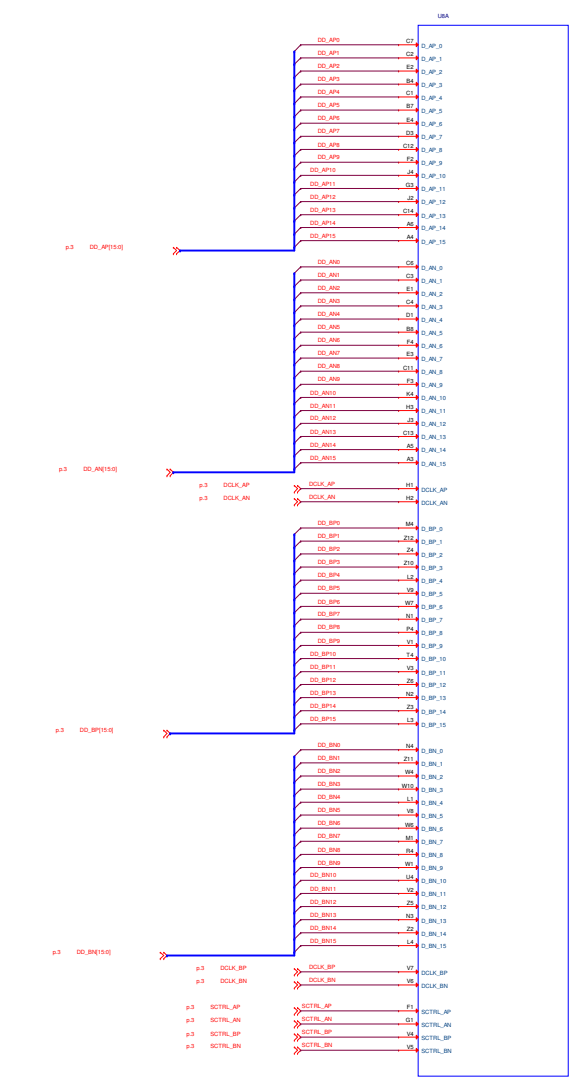
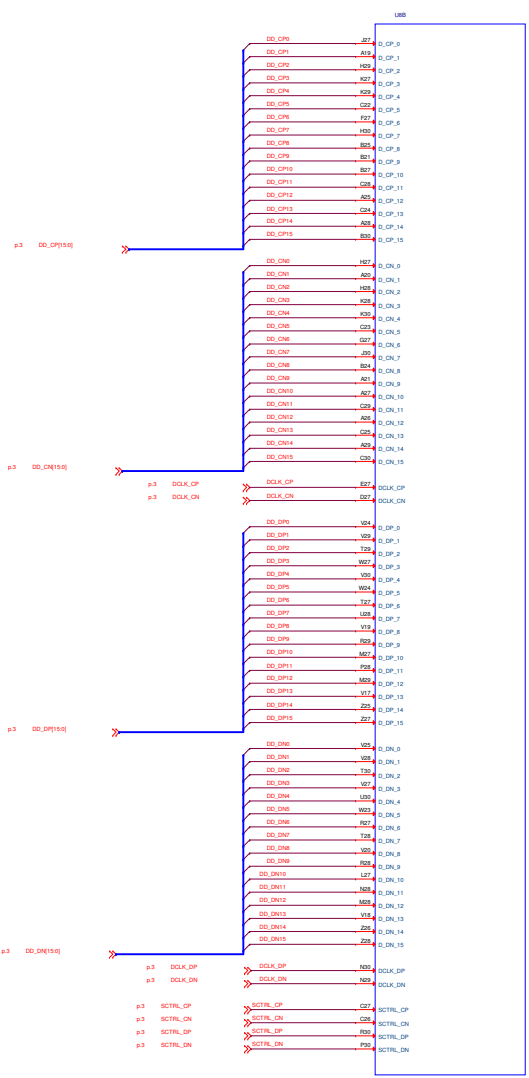
Power Down Circuitry



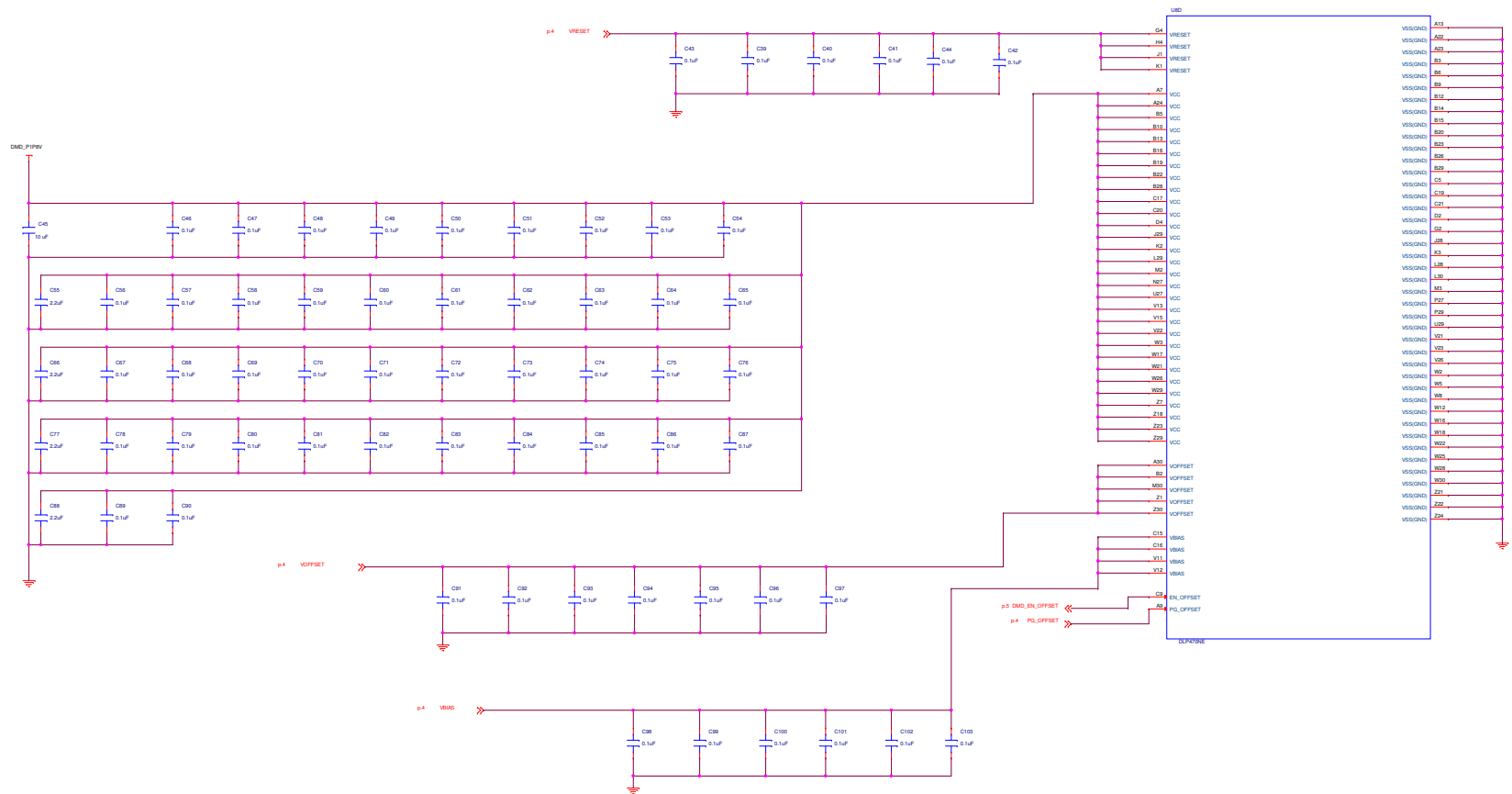
DMD Power Supplies

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	Rev. Using	8/24/2016	2515294	A
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DMD Data/Control



DMD Power/Gnd

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	Ben Lihng	8/4/2016		
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